

COG type LCD Module Specification

CUSTOMER : _____

MODULE NO.: **DC12864B-TFH#**

APPROVED BY: (FOR CUSTOMER USE ONLY)	PCB VERSION: DATA:
--	---------------------------

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
ISSUED DATE:			

Densitron Corporation
K2 bldg.6F No.3-4-4.Omori-Kita.Ota-Ku.143-0016
www.densitron.jp
Phone: +81-3-3767-9701 Fax:+81-3-3767-9709

MODLE NO :

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2007.11.30		First issue

Contents

1. Module Classification Information
2. Precautions in use of LCD Modules
3. General Specification
4. Absolute Maximum Ratings
5. Electrical Characteristics
6. Optical Characteristics
7. Interface Pin Function
8. Contour Drawing & Block Diagram
9. Timing Characteristics
10. Display Command
11. Reliability
12. Backlight Information
13. Inspection specification
14. Material List of Components for RoHs

1.Module Classification Information

DC 12864 B— T F H #
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ① Supplier : Densitron®Displays
- ② Display Type : C→COG Type
- ③ Display Font : 128 x 64 dots
- ④ Model serials no.
- ⑤ Backlight Type : N→Without backlight T→LED, White
 B→EL, Blue green A→LED, Amber
 D→EL, Green R→LED, Red
 W→EL, White O→LED, Orange
 F→CCFL, White G→LED, Green
 Y→LED, Yellow Green P→LED, Blue
- ⑥ LCD Mode : B→TN Positive, Gray T→FSTN Negative
 N→TN Negative,
 G→STN Positive, Gray
 Y→STN Positive, Yellow Green
 M→STN Negative, Blue
 F→FSTN Positive
- ⑦ LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00
 Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00
 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00
 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00
 B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00
 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00
- ⑧ Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.

3.General Specification

Item	Dimension	Unit
Number of Characters	128 x 64 dots	—
Module dimension	89.7x 49.8 x12.1(MAX)	mm
View area	69.0 x 36.5	mm
Active area	63.97 x31.97	mm
Dot size	0.47 x0.47	mm
Dot pitch	0.5 x 0.5	mm
LCD type	FSTN Positive, Transflective	
Duty	1/65 , 1/9 Bias	
View direction	6 o'clock	
Backlight Type	LED White	

4. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	°C
Storage Temperature	T_{ST}	-30	—	+80	°C
Supply voltage for Logic	V_{DD}	0.3	—	5.0	V
Supply Voltage for LCD Driver	V_{OUT}, V_0	0.3		18.0	V

5. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	2.7	3.0	3.3	V
Supply Voltage For LCM	V_0-V_{SS}	$T_a=-20^{\circ}C$	9.5	9.8	10.5	V
		$T_a=25^{\circ}C$	9.2	9.45	9.7	V
		$T_a=70^{\circ}C$	8.95	9.2	9.45	V
Input High Volt.	V_{IH}	—	$0.8 V_{DD}$	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	V_{SS}	—	$0.2 V_{DD}$	V
Output High Volt.	V_{OH}	$I_{OUT}=-0.5mA$	$0.8 V_{DD}$	—	V_{DD}	V
Output Low Volt.	V_{OL}	$I_{OUT}=0.5mA$	V_{SS}	—	$0.2V_{DD}$	V
Supply Current(No include LED Backlight)	I_{DD}	$V_{DD}=3.0V$		0.60	2.0	mA

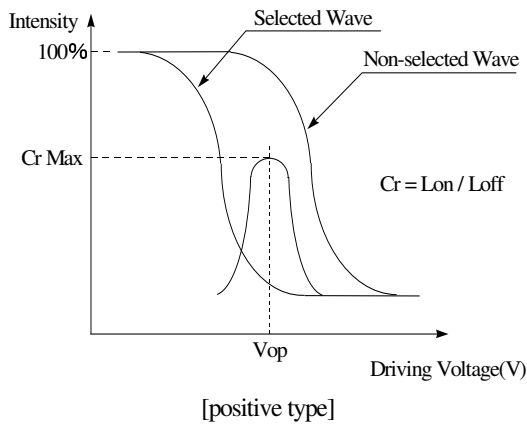
NOTE: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state

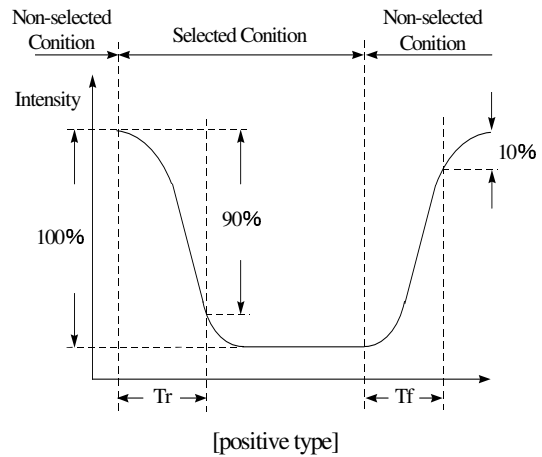
6. Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	$CR \geq 2$	30	—	40	deg
	(H) φ	$CR \geq 2$	-40	—	40	deg
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	100	280	ms
	T fall	—	—	180	330	ms

Definition of Operation Voltage (Vop)



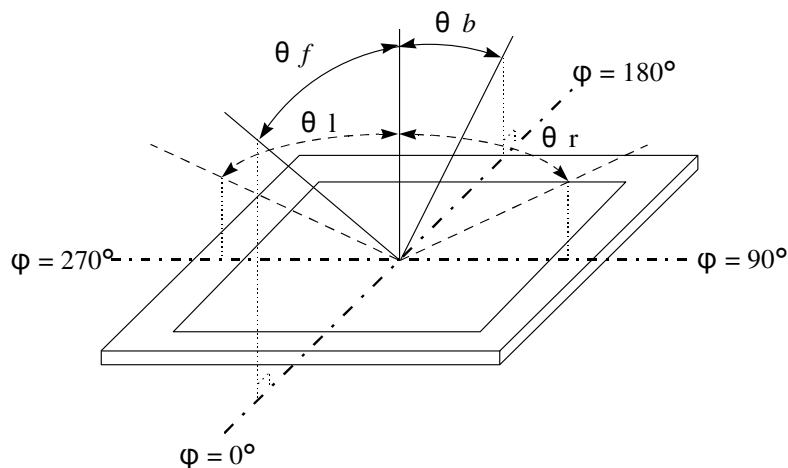
Definition of Response Time (Tr, Tf)



Conditions :

- Operating Voltage : Vop
- Viewing Angle (θ , φ) : 0° , 0°
- Frame Frequency : 64 HZ
- Driving Waveform : 1/N duty, 1/a bias

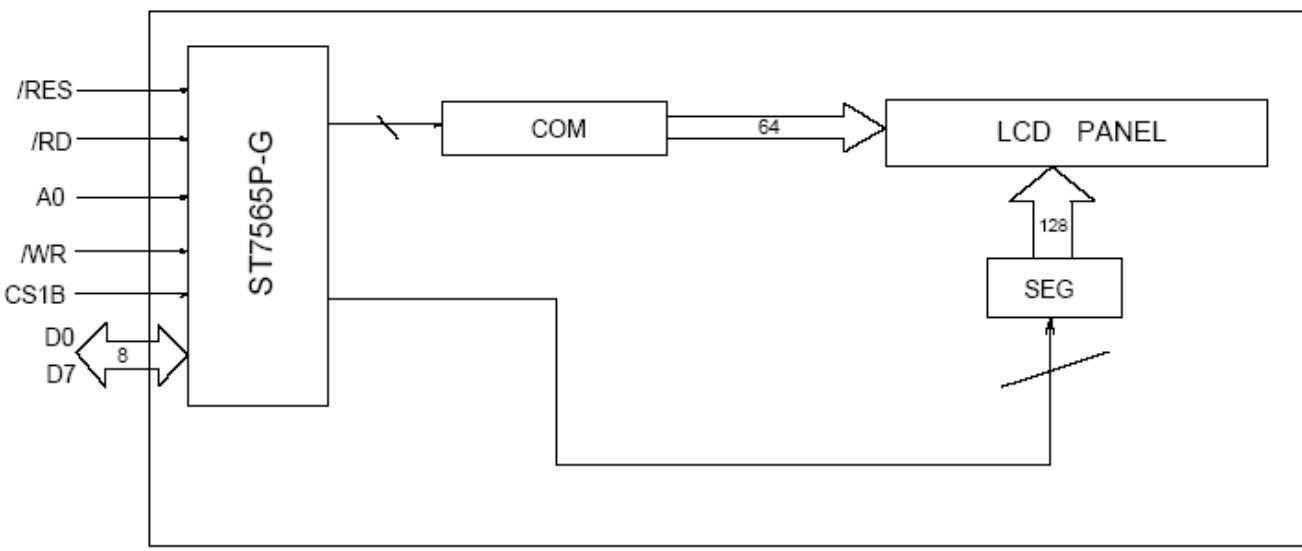
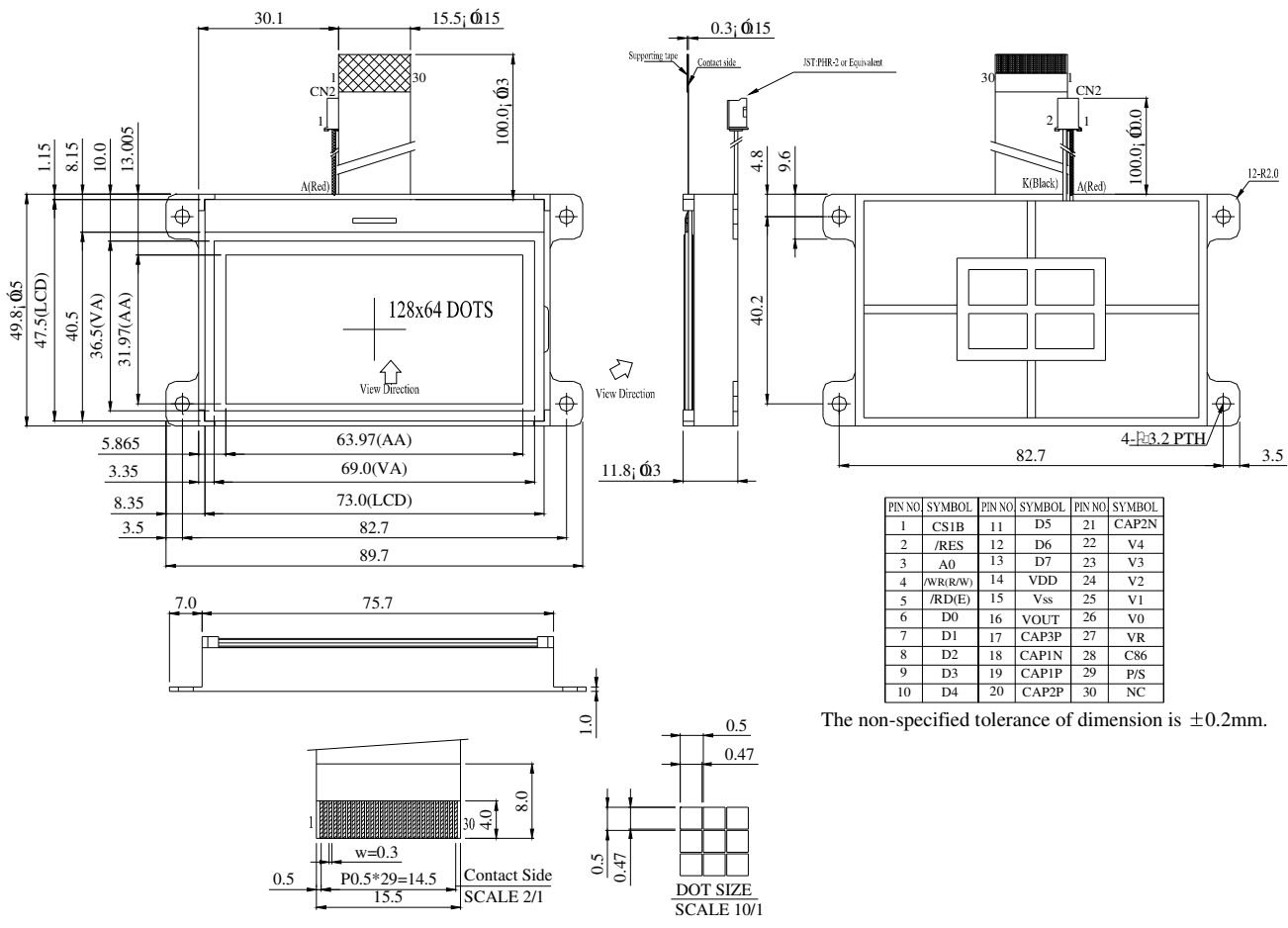
Definition of viewing angle ($CR \geq 2$)



7.Interface Pin Function

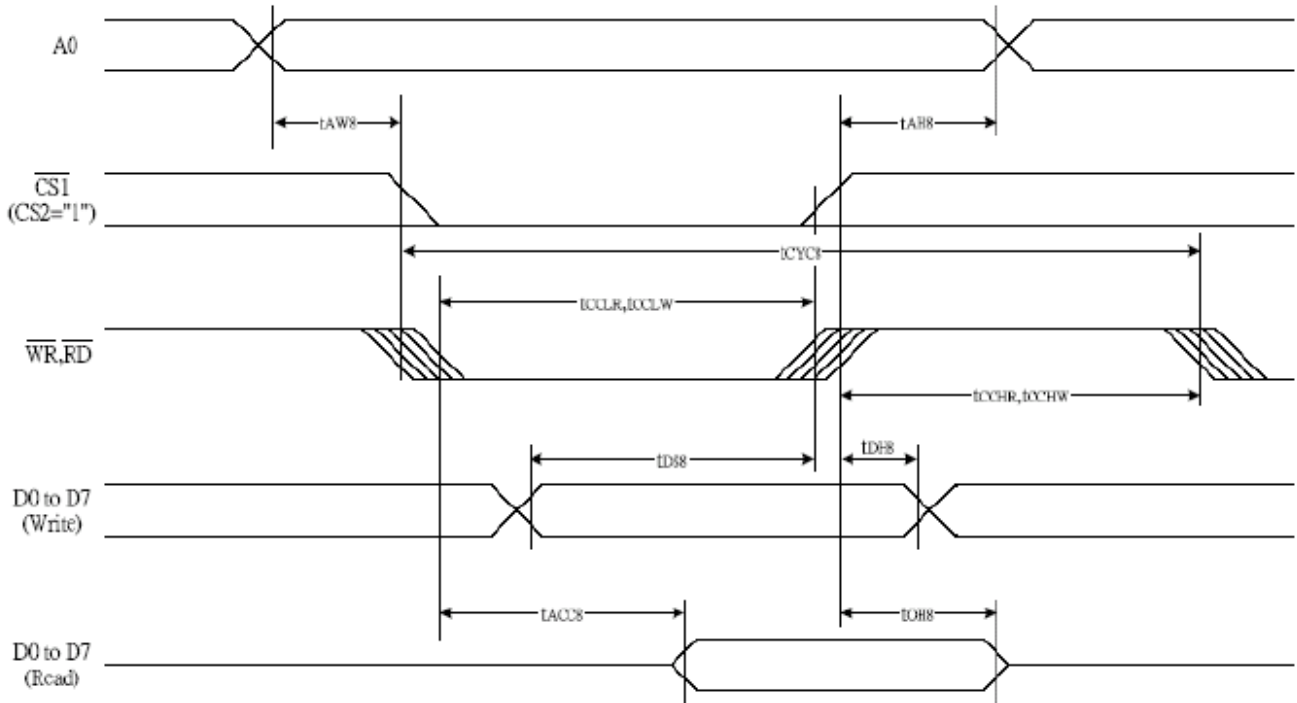
Pin No.	Symbol	I/O	Description
1	/CS1B	I	This is the chip select signal.
2	/RES	I	When RES is set to “L”, the setting are initialized.
3	A0	I	This is connect to the least significant bit of the Norman MPU address bus, and it determines whether the data bits are data or a command.
4	/WR(R/W)	I	The data bus are latched at the rising edge of the WR signal
5	/RD(E)	I	The data bus is in output status when this signal is “L”
6~13	D0~ D7	I/O	This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus.
14	VDD	Power Supply	Power supply
15	VSS	Power Supply	Ground
16	VOUT	O	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD
17	CAP3P	O	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
18	CAP1N	O	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.
19	CAP1P	O	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
20	CAP2P	O	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
21	CAP2N	O	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal.
22~26	V4~ V0	Power Supply	This is a multi-level power supply for the liquid crystal drive.
27	VR	I	Output voltage regulator terminal. Provides the voltage between VSS and V0 through a resistive voltage divider.
28	C86	I	This is the MPU interface switch terminal.
29	P/S	I	This is the parallel data input/serial data input switch terminal.
30	NC	-	No connection.

8. Contour Drawing & Block Diagram



9. Timing Characteristics

9-1. 8080 Series MPU



($V_{DD} = 3.3V$, $T_a = 25^\circ C$)

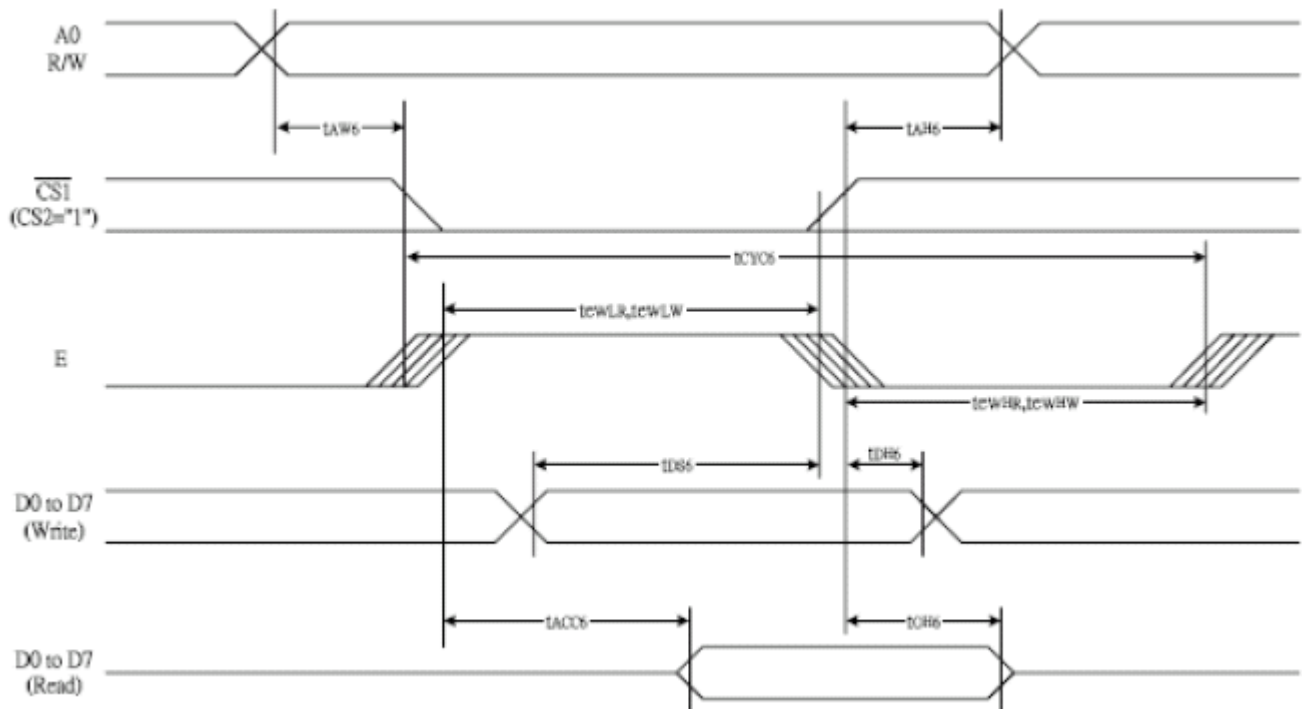
Item	Signal	Symbol	Condition	Rating		Units
				Min.	Max.	
Address hold time	A0	t_{AH8}		0	—	Ns
Address setup time		t_{AW8}		0	—	
System cycle time		t_{CYC8}		240	—	
Enable L pulse width (WRITE)	WR	t_{CCLW}		80	—	
Enable H pulse width (WRITE)		t_{CCHW}		80	—	
Enable L pulse width (READ)	RD	t_{CCLR}		140	—	
Enable H pulse width (READ)		t_{CCHR}		80	—	
WRITE Data setup time	D0 to D7	t_{DS8}		40	—	
WRITE Address hold time		t_{DH8}		0	—	
READ access time		t_{ACC8}	$C_L = 100 \text{ pF}$	—	70	
READ Output disable time		t_{OH8}	$C_L = 100 \text{ pF}$	5	50	

*1 The input signal rise time and fall time (t_r , t_f) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \leq (t_{CYC8} - t_{CCLW} - t_{CCHW})$ for $(t_r + t_f) \leq (t_{CYC8} - t_{CCLR} - t_{CCHR})$ are specified.

*2 All timing is specified using 20% and 80% of V_{DD} as the reference.

*3 t_{CCLW} and t_{CCLR} are specified as the overlap between /CS1 being "L" (CS2 = "H") and /WR and /RD being at the "L" level.

8-2. 6800-Series MPU



($V_{DD} = 3.3\text{ V}$, $T_a = 25^\circ\text{C}$)

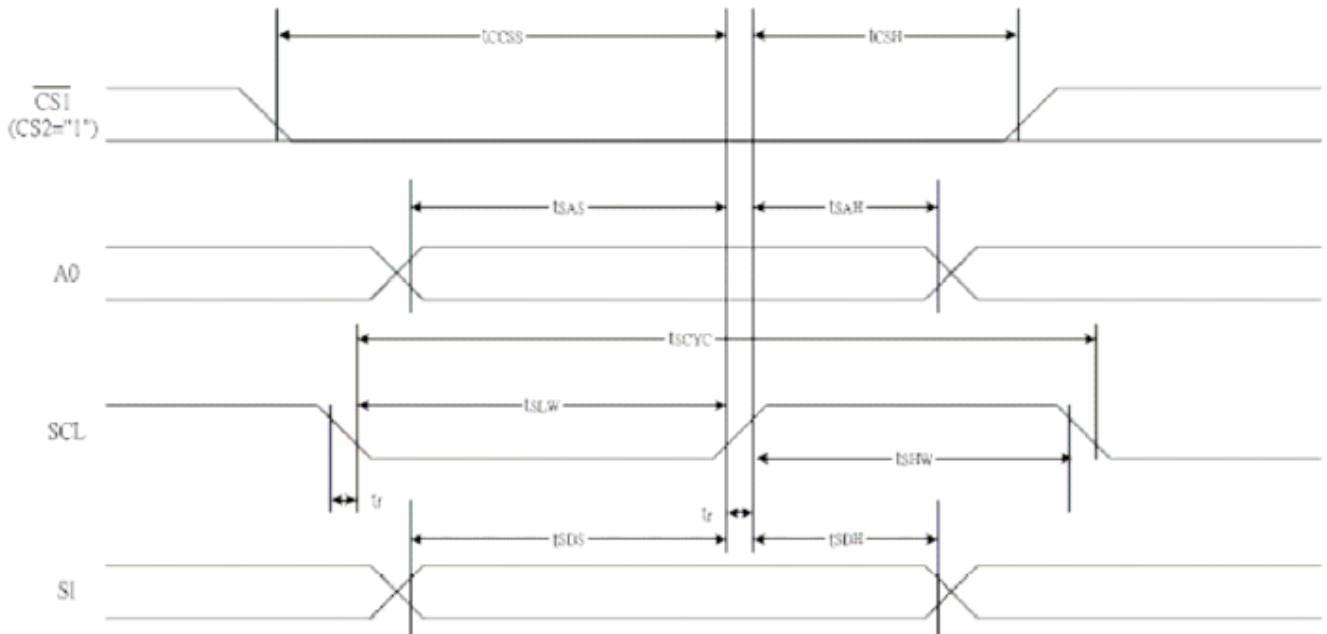
Item	Signal	Symbol	Condition	Rating		Units
				Min.	Max.	
Address hold time	A0	t_{AH6}		0	—	ns
Address setup time		t_{AW6}		0	—	
System cycle time		t_{CYC6}		240	—	
Enable L pulse width (WRITE)	WR	t_{EWLW}		80	—	
Enable H pulse width (WRITE)		t_{EHWLW}		80	—	
Enable L pulse width (READ)	RD	t_{EHLR}		80	—	
Enable H pulse width (READ)		t_{EHLR}		140	—	
WRITE Data setup time	D0 to D7	t_{DS6}		40	—	
WRITE Address hold time		t_{DH6}		0	—	
READ access time		t_{ACC6}	$C_L = 100\text{ pF}$	—	70	
READ Output disable time		t_{OH6}	$C_L = 100\text{ pF}$	5	50	

*1 The input signal rise time and fall time (t_r , t_f) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \leq (t_{CYC6} - t_{EWLW} - t_{EHWLW})$ for $(t_r + t_f) \leq (t_{CYC6} - t_{EHLR} - t_{EHLR})$ are specified.

*2 All timing is specified using 20% and 80% of V_{DD} as the reference.

*3 t_{EWLW} and t_{EHLR} are specified as the overlap between CS1 being "L" (CS2 = "H") and E.

8-3. The Serial Interface



($V_{DD} = 3.3V$, $T_a = 25^\circ C$)

Item	Signal	Symbol	Condition	Rating		Units
				Min.	Max.	
Serial Clock Period	SCL	T_{SCYC}		50	—	ns
SCL "H" pulse width		T_{SNW}		25	—	
SCL "L" pulse width		T_{SLW}		25	—	
Address setup time	A0	T_{SAS}		20	—	
Address hold time		T_{SAH}		10	—	
Data setup time	SI	T_{SDS}		20	—	
Data hold time		T_{SDH}		10	—	
CS-SCL time	CS	T_{CSS}		20	—	
CS-SCL time		T_{CSH}		40	—	

*1 The input signal rise and fall time (t_r , t_f) are specified at 15 ns or less.

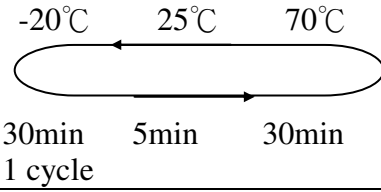
*2 All timing is specified using 20% and 80% of V_{DD} as the standard.

10. Display Command

Command	Command Code										Function	
	A0	/RD	/WR	D7	D6	D5	D4	D3	D2	D1		D0
(1) Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0	1
(2) Display start line set	0	1	0	0	1	Display start address						Sets the display RAM display start line address
(3) Page address set	0	1	0	1	0	1	1	Page address				Sets the display RAM page address
(4) Column address set upper bit	0	1	0	0	0	0	1	Most significant column address				Sets the most significant 4 bits of the display RAM column address.
Column address set lower bit	0	1	0	0	0	0	0	Least significant column address				Sets the least significant 4 bits of the display RAM column address.
(5) Status read	0	0	1	Status				0	0	0	0	0
(6) Display data write	1	1	0	Write data								Writes to the display RAM
(7) Display data read	1	0	1	Read data								Reads from the display RAM
(8) ADC select	0	1	0	1	0	1	0	0	0	0	0	1
(9) Display normal/reverse	0	1	0	1	0	1	0	0	1	1	0	1
(10) Display all points ON/OFF	0	1	0	1	0	1	0	0	1	0	0	1
(11) LCD bias set	0	1	0	1	0	1	0	0	0	1	0	1
(12) Read/modify/write	0	1	0	1	1	1	0	0	0	0	0	0
(13) End	0	1	0	1	1	1	0	1	1	1	0	0
(14) Reset	0	1	0	1	1	1	0	0	0	1	0	0
(15) Common output mode select	0	1	0	1	1	0	0	0	1	*	*	*
(16) Power control set	0	1	0	0	0	1	0	1	Operating mode			Select internal power supply operating mode
(17) V ₀ voltage regulator internal resistor ratio set	0	1	0	0	0	1	0	0	Resistor ratio			Select internal resistor ratio(R _b /R _a) mode
(18) Electronic volume mode set	0	1	0	1	0	0	0	0	0	0	0	1
Electronic volume register set				0	0	Electronic volume value						Set the V ₀ output voltage electronic volume register
(19) Static Indicator ON/OFF	0	1	0	1	0	1	0	1	1	0	0	1
Static Indicator register set				0	0	0	0	0	0	0	0	Mode
(20) Booster ratio set	0	1	0	1	1	1	1	1	0	0	0	0
				0	0	0	0	0	0	0	step-up value	
(21) Power saver												
(22) NOP	0	1	0	1	1	1	0	0	0	1	1	1
(23) Test	0	1	0	1	1	1	1	*	*	*	*	*

11. Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

Environmental Test			
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	—
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60 °C, 90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C, 90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	—
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V, RS=1.5kΩ CS=100pF 1 time	—

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

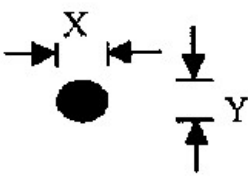
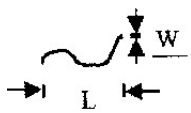
12.Backlight Information

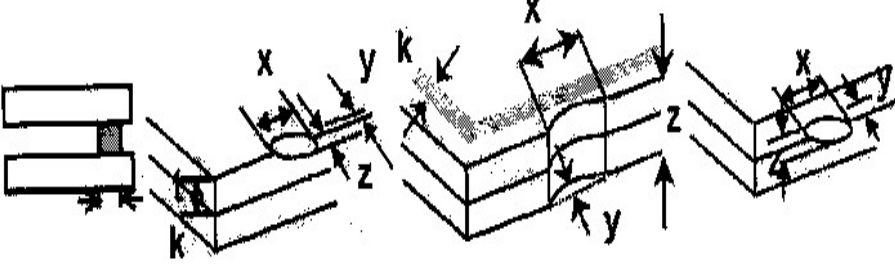
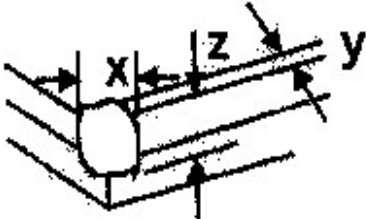
Specification

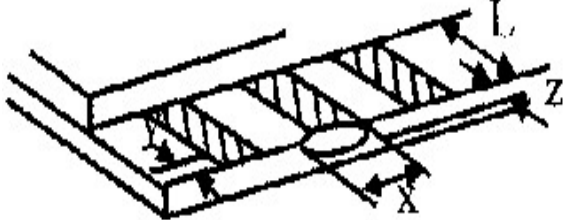
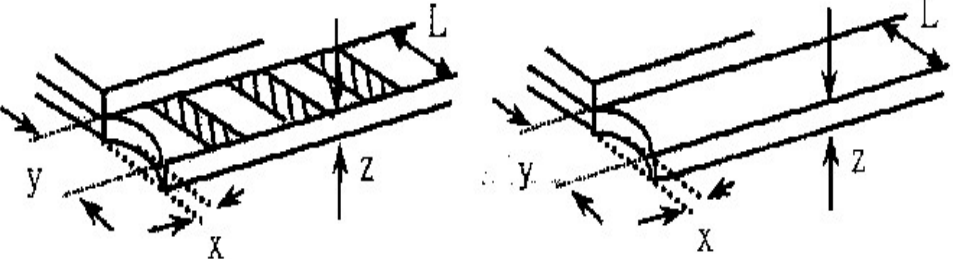
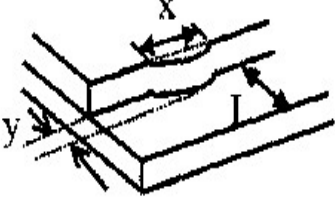
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	I _{LED}	61.2	72	100	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	V _R	—	—	5	V	—
Luminous Intensity (Without LCD)	I _V	600	800	—	CD/M ²	I _{LED} =72mA
Wave Length	X	0.27	0.3	0.33		I _{LED} =72mA
	Y	0.26	0.29	0.32		
Life Time	—	—	10000	—	Hr.	I _{LED} ≤ 72mA
Color	White					

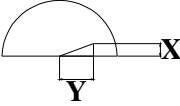
**Note: The LED of B/L is drive by current only ; driving voltage is only for reference
To make driving current in safety area (waste current between minimum and maximum).**

13. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$  <table border="1" data-bbox="874 1041 1353 1294"> <thead> <tr> <th>SIZE</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>1</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> </tr> </tbody> </table>	SIZE	Acceptable Q TY	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	1	$0.25 < \Phi$	0	2.5		
		SIZE	Acceptable Q TY												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	1														
$0.25 < \Phi$	0														
3.2 Line type : (As following drawing)  <table border="1" data-bbox="710 1400 1353 1646"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> </tr> </tbody> </table>	Length	Width	Acceptable Q TY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$	As round type	2.5
Length	Width	Acceptable Q TY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" data-bbox="842 1697 1353 1998"> <thead> <tr> <th>Size Φ</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total Q TY</td> <td>3</td> </tr> </tbody> </table>	Size Φ	Acceptable Q TY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total Q TY	3	2.5
Size Φ	Acceptable Q TY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total Q TY	3														

NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:</p> <p>6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="422 945 1318 1137"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="422 1529 1318 1722"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL																
06	Glass crack	<p>Symbols :</p> <p>x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="355 701 1265 790"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>Z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="427 1126 1265 1216"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="762 1440 1273 1529"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	Z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
y: Chip width	x: Chip length	Z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB \ COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	

14. Material List of Components for RoHs

1. Densitron ®Displays hereby declares that all of or part of products (with the mark “#”in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement :

(1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp. :

Reflow : 250C degree,30 seconds Max. ;

Connector soldering wave or hand soldering : 320C degree, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5C degree ;

Recommended customer’s soldering temp. of connector : 280C degree, 3 seconds.